DOCUMENT CHANGE REQUEST

DCR number 1479	Changes required for: General	Originator: Sylvie PeronA
Date: 2023/09/19	Date sent: 2021/11/15	Organisation: STMicroelectronics
Status: IMPLEMENTED		

Title:	Requirements for Lead Materials and Finishes for Components for Space Application		
Number:	23500	Issue:	7

Other documents affected:

Page:

7

Paragraph:

3.3

Original wording:

Type 4 - Hot solder dip
....For leaded packages the coating shall have a thickness of 2.5µm to 13µm.....

Proposed wording:

Type 4 - Hot solder dip
...for leaded packages with rectangular section, the coating shall have a minimum thickness limit of 5.08µm ; For leaded packages with round section, the coating shall have a minimum thickness limit of 1.52 µm....

Justification:

Having a unique requirement common to US standards defined in MIL-PRF-38535 Table A-III for IC's or MIL-PRF-19500 Table H-I for Discrete for coating thickness.
Prior writing this DCR, it has been approved by CNES and ESCC

Attachments:

escc23500iss_draft_8a_for_review.docx

Modifications:

The original proposed wording to Para. 3.3 Type 4 is modified as follows; see attached specification mark-up 23500 Draft 8A:

Replace with the following:
For leaded packages with round leads, the thickness of the solder shall be 2.5µm minimum.
For leaded packages with rectangular leads, the thickness of the solder shall be 5.08µm minimum.

Approval signature:



Date signed:
2023-09-19